

SEMITOP[®] 3

IGBT Module

SK25MLI065

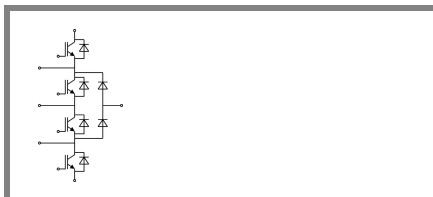
Target Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- Ultra Fast NPT IGBT technology
- CAL technology FWD

Typical Applications

- Multi level inverter



MLI

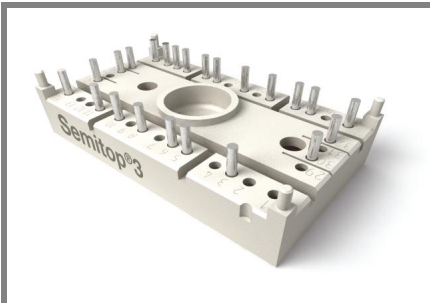
Absolute Maximum Ratings		$T_s = 25\text{ °C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
IGBT			
V_{CES}	$T_j = 25\text{ °C}$	600	V
I_C	$T_j = 125\text{ °C}$	$T_s = 25\text{ °C}$	30 A
		$T_s = 80\text{ °C}$	22 A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$	60	A
V_{GES}		± 20	V
t_{psc}	$V_{CC} = 300\text{ V}; V_{GE} \leq 20\text{ V}; T_j = 125\text{ °C}$ $V_{CES} < 600\text{ V}$	10	μs

Inverse Diode		$T_s = 25\text{ °C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
I_F	$T_j = 150\text{ °C}$	$T_s = 25\text{ °C}$	36 A
		$T_s = 80\text{ °C}$	24 A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$		A
I_{FSM}	$t_p = 10\text{ ms}; \text{half sine wave } T_j = 150\text{ °C}$	200	A

Freewheeling Diode		$T_{case} = 25\text{ °C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
I_F	$T_j = 150\text{ °C}$	$T_{case} = 25\text{ °C}$	36 A
		$T_{case} = 80\text{ °C}$	24 A
I_{FRM}			A
I_{FSM}	$t_p = 10\text{ ms}; \text{half sine wave } T_j = 150\text{ °C}$	200	A

Module		$T_s = 25\text{ °C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
$I_{t(RMS)}$			A
T_{vj}		-40 ... +150	$^{\circ}\text{C}$
T_{stg}		-40 ... +125	$^{\circ}\text{C}$
V_{isol}	AC, 1 min.	2500	V

Characteristics		$T_s = 25\text{ °C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 0,7\text{ mA}$	3	4	5	V
I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES} T_j = 25\text{ °C}$			0,0022	mA
I_{GES}	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V } T_j = 25\text{ °C}$			120	nA
V_{CE0}		$T_j = 25\text{ °C}$	1,4	1,9	V
		$T_j = 125\text{ °C}$	1,7	2,2	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25\text{ °C}$			$\text{m}\Omega$
		$T_j = 125\text{ °C}$		44	$\text{m}\Omega$
$V_{CE(sat)}$	$I_{Cnom} = 30\text{ A}, V_{GE} = 15\text{ V}$	$T_j = 25\text{ °C}_{chiplev.}$	1,8		V
		$T_j = 125\text{ °C}_{chiplev.}$	2,1		V
C_{ies}	$V_{CE} = 25, V_{GE} = 0\text{ V} f = 1\text{ MHz}$		1,6		nF
C_{oes}		0,15		nF	
C_{res}		0,09		nF	
$t_{d(on)}$	$R_{Gon} = 33\ \Omega$	$V_{CC} = 300\text{ V}$ $I_{Cnom} = 25\text{ A}$	30		ns
t_r			25		ns
E_{on}			0,75		mJ
$t_{d(off)}$	$R_{Goff} = 33\ \Omega$	$T_j = 125\text{ °C}$ $V_{GE} = \pm 15\text{ V}$	250		ns
t_f			15		ns
E_{off}			0,6		mJ
$R_{th(j-s)}$	per IGBT			1,4	K/W



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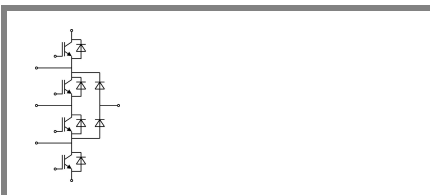
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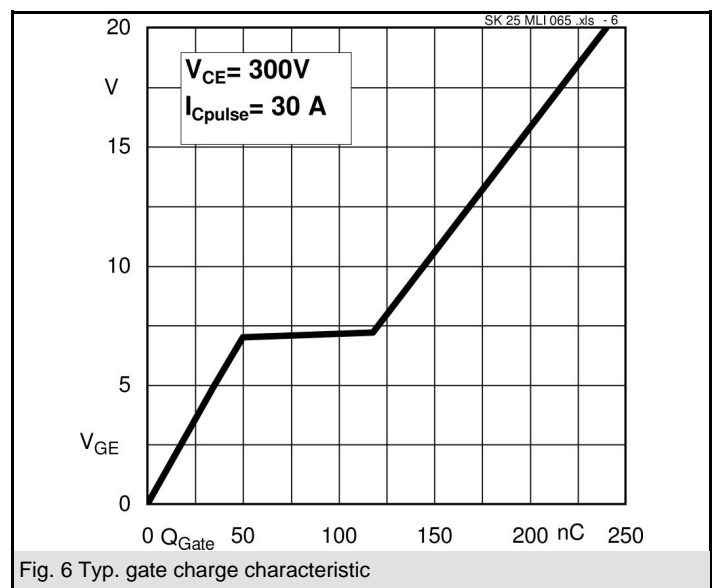
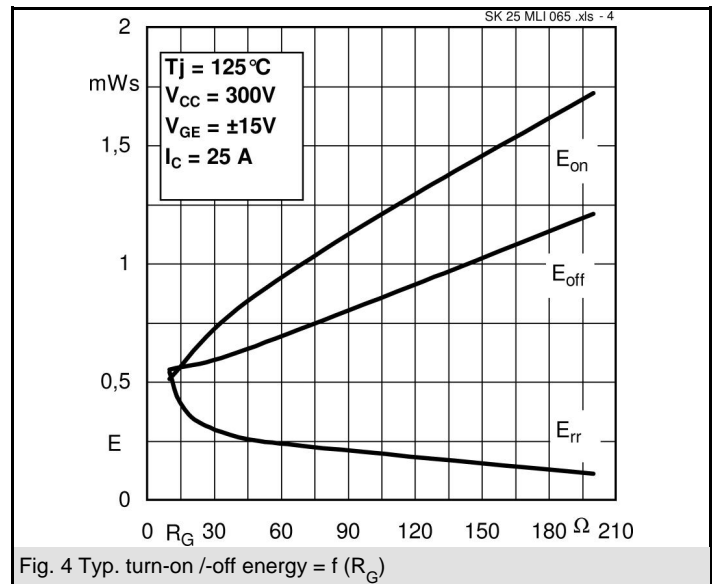
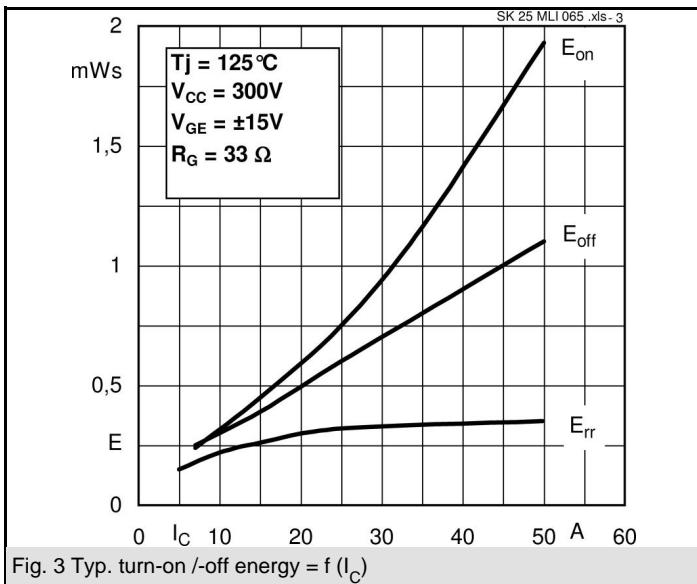
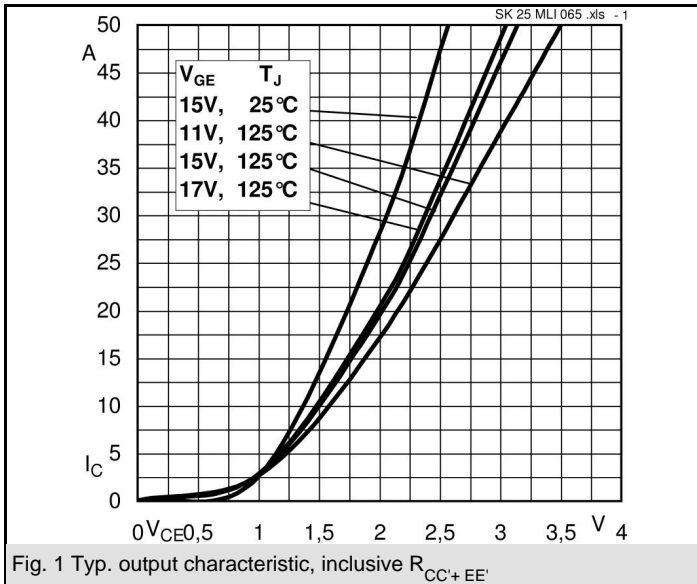


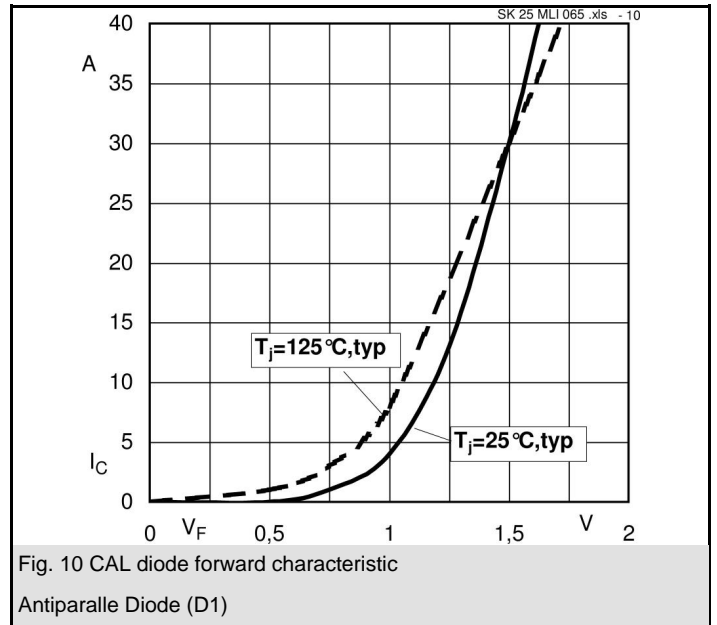
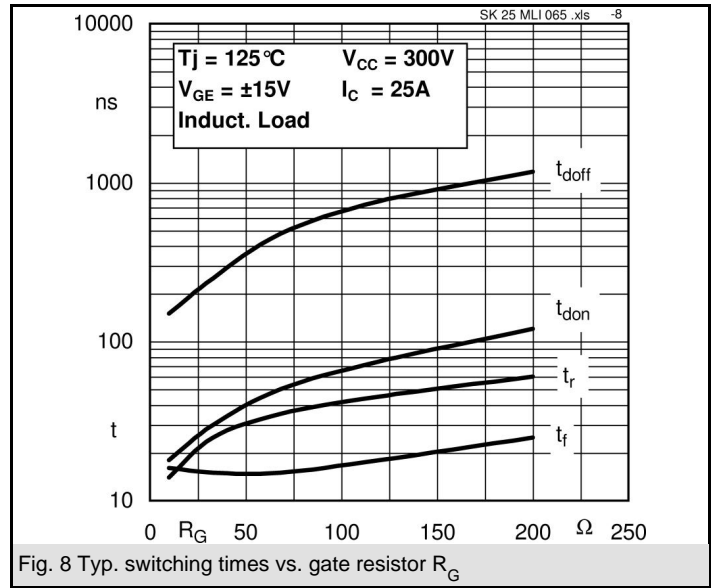
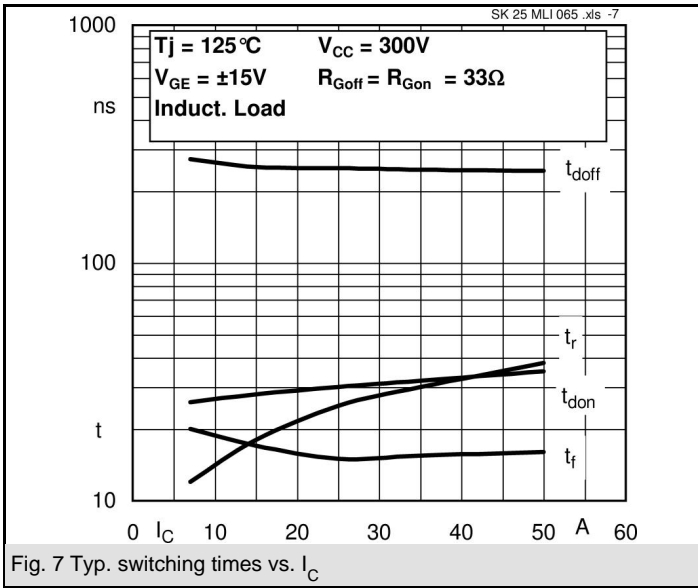
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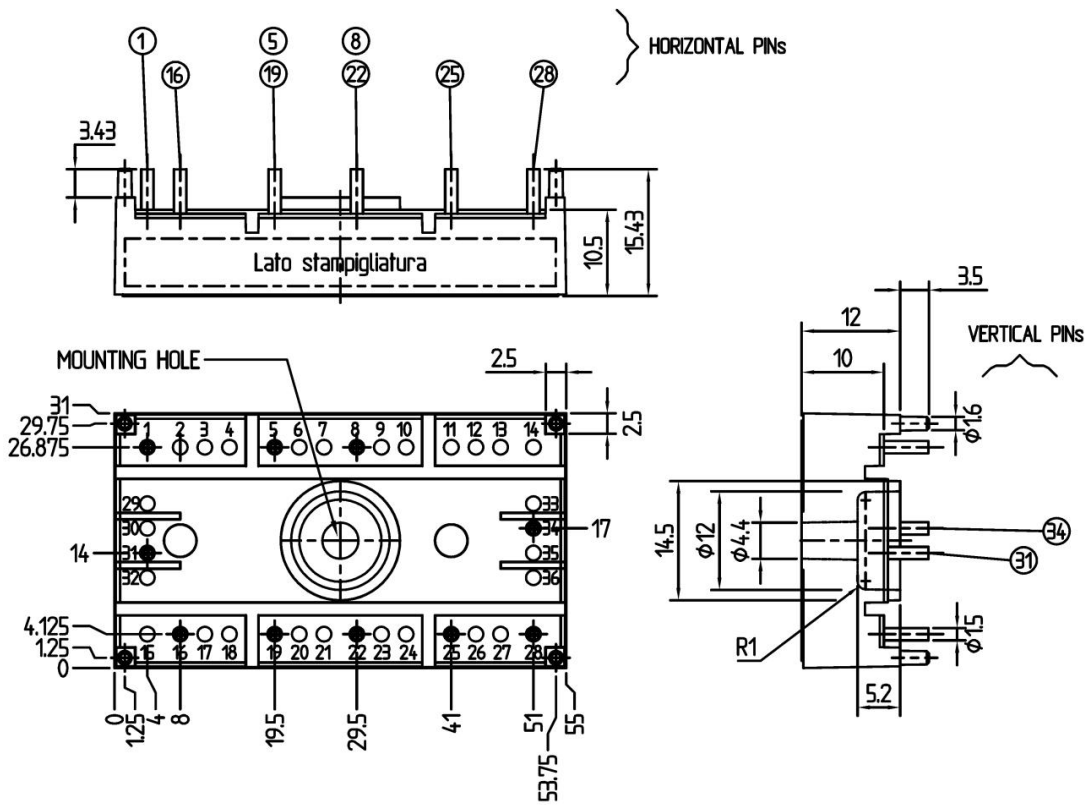
Characteristics						
Symbol	Conditions		min.	typ.	max.	Units
Antiparallel Diode (D1)						
$V_F = V_{EC}$	$I_{Fnom} = 25 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$		1,45		V
		$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$		1,4		V
V_{F0}		$T_j = 25 \text{ }^\circ\text{C}$				V
		$T_j = 125 \text{ }^\circ\text{C}$		0,85		V
r_F		$T_j = 25 \text{ }^\circ\text{C}$				mΩ
		$T_j = 125 \text{ }^\circ\text{C}$		22		mΩ
I_{RRM}	$I_{Fnom} = 25 \text{ A}$	$T_j = 125 \text{ }^\circ\text{C}$				A
Q_{rr}	$di/dt = -2400 \text{ A}/\mu\text{s}$					μC
E_{rr}	$V_R = 300\text{V}$			0,32		mJ
$R_{th(j-s)D}$	per diode				1,7	K/W
Freewheeling Diode (D2)						
$V_F = V_{EC}$	$I_{Fnom} = 25 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$		1,45		V
		$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$		1,4		V
V_{F0}		$T_j = 125 \text{ }^\circ\text{C}$		0,85		V
r_F		$T_j = 125 \text{ }^\circ\text{C}$		22		V
I_{RRM}	$I_{Fnom} = 25 \text{ A}$	$T_j = 125 \text{ }^\circ\text{C}$				A
Q_{rr}	$di/dt = -2400 \text{ A}/\mu\text{s}$					μC
E_{rr}	$V_R = 300\text{V}$			0,32		mJ
$R_{th(j-s)FD}$	per diode				1,7	K/W
M_s	to heat sink		2,25		2,5	Nm
w				30		g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.







Case T 76 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)

